



CeraDiodes

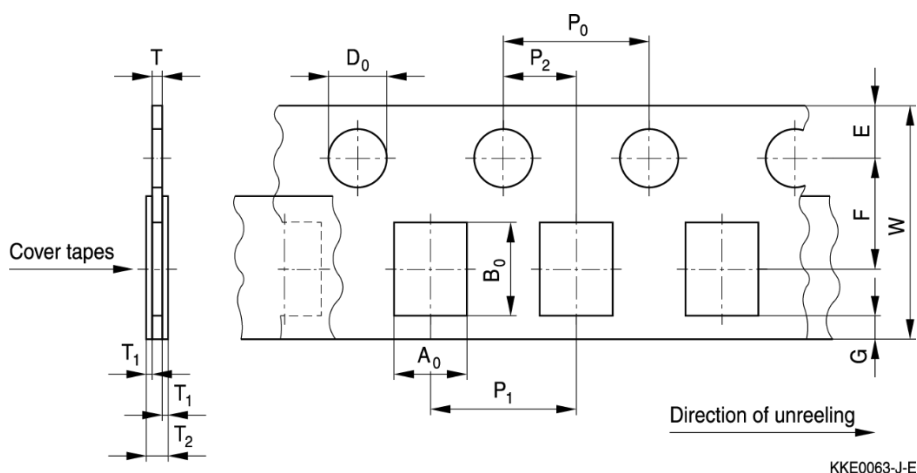
Taping and packing

Date: November 2025

Taping and Packing

1 Taping and packing for chip and array CeraDiodes

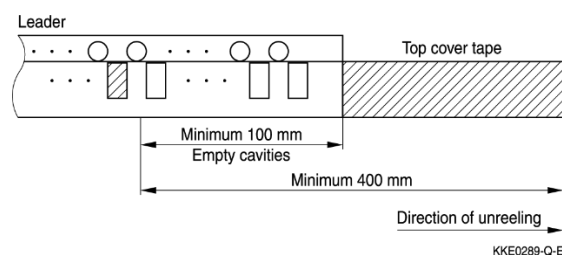
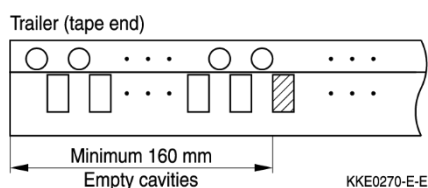
1.1 Cardboard tape (taping to IEC 60286-3)



Dimensions in mm

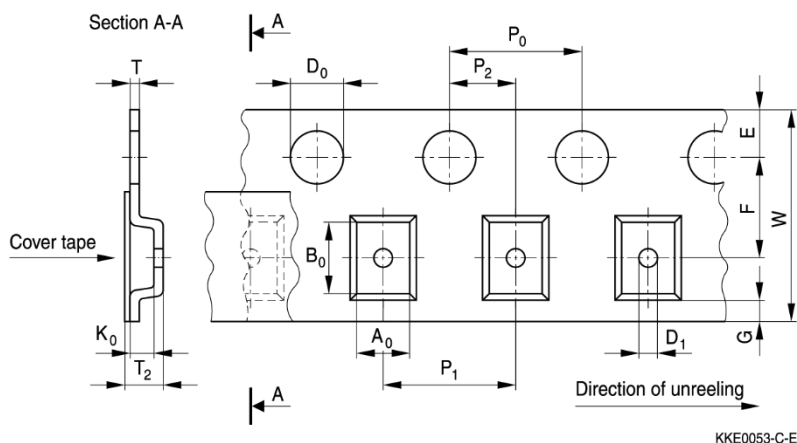
Case size (inch) (mm)		0201 0603	0402 1005	0603 1608	1003 2508	0508 1220	Tolerance
Compartment width	A_0	0.38 ± 0.05	0.6	0.95	1.0	1.6	± 0.2
Compartment length	B_0	0.68 ± 0.05	1.15	1.8	2.85	2.4	± 0.2
Sprocket hole diameter	D_0	1.5 ± 0.1	1.5	1.5	1.5	1.5	$+0.1/-0$
Sprocket hole pitch	P_0	$4.0 \pm 0.1^{1)}$	4.0	4.0	4.0	4.0	$\pm 0.1^{1)}$
Distance center hole to center compartment	P_2	2.0 ± 0.05	2.0	2.0	2.0	2.0	± 0.05
Pitch of component compartments	P_1	2.0 ± 0.05	2.0	4.0	4.0	4.0	± 0.1
Tape width	W	8.0 ± 0.3	8.0	8.0	8.0	8.0	± 0.3
Distance edge to center of hole	E	1.75 ± 0.1	1.75	1.75	1.75	1.75	± 0.1
Distance center hole to center compartment	F	3.5 ± 0.05	3.5	3.5	3.5	3.5	± 0.05
Distance compartment to edge	G	0.75 min.	0.75	0.75	0.75	0.75	min.
Thickness tape	T	0.42 ± 0.02	0.6	0.9	0.95	0.95	max.
Overall thickness	T_2	0.4 min.	0.7	1.1	1.1	1.10	max.

1) $\leq \pm 0.2$ mm over 10 sprocket holes



Taping and Packing

1.2 Blister tape (taping to IEC 60286-3)

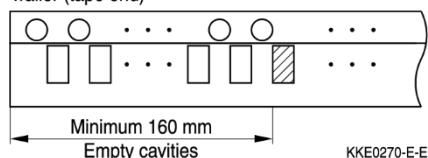


Dimensions in mm

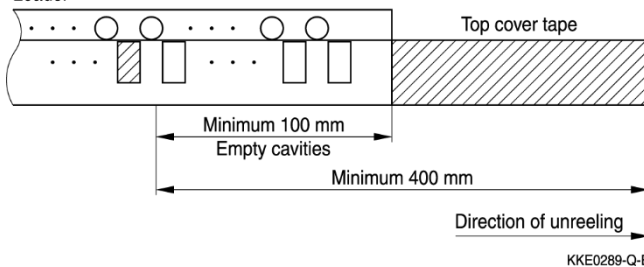
Case size (inch) (mm)		0506 1216	0612 1632	1012 2532	Tolerance
Compartment width	A ₀	1.5	1.8	2.8	±0.2
Compartment length	B ₀	1.8	3.4	3.5	±0.2
Compartment height	K ₀	0.8	1.8	1.8	max
Sprocket hole diameter	D ₀	1.5	1.5	1.5	+0.1/ -0
Compartment hole diameter	D ₁	0.3	0.3	0.3	Min.
Sprocket hole pitch	P ₀	4.0	4.0	4.0	±0.1 ¹⁾
Distance center hole to center compartment	P ₂	2.0	2.0	2.0	±0.05
Pitch of component compartments	P ₁	4.0	4.0	4.0	±0.1
Tape width	W	8.0	8.0	8.0	±0.3
Distance edge to center of hole	E	1.75	1.75	1.75	±0.1
Distance center hole to center compartment	F	3.5	3.5	3.5	±0.05
Distance compartment to edge	G	0.75	0.75	0.75	min.
Thickness tape	T	0.3	0.3	0.3	max.
Overall thickness	T ₂	1.3	2.5	2.5	max.

1) $\leq \pm 0.2$ mm over 10 sprocket holes

Trailer (tape end)

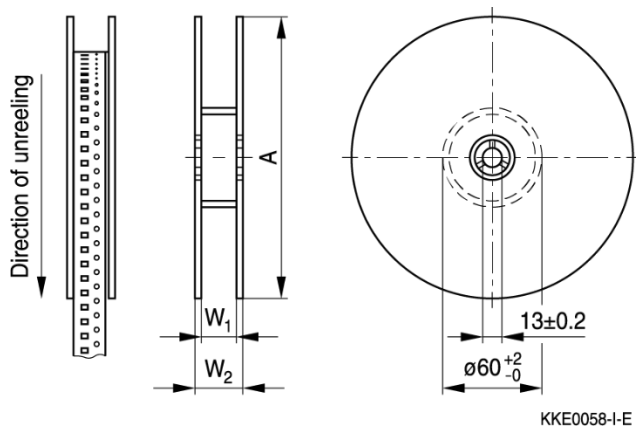


Leader



Taping and Packing

1.3 Reel packing



Dimensions in mm

		Dimensions	Tolerance	Dimensions	Tolerance
Reel diameter	A	180	+0/ -3	330	+0/ -2
Reel width (inside)	W_1	8.4	+1.5/ -0	8.4	+1.5/ -0
Reel width (outside)	W_2	14.4	max.	14.4	max.

Package: 8-mm tape

Reel material: Plastic

1.4 Packing units

Case size (inch) / (mm)	Ø 180-mm reel pieces	Ø 330-mm reel pieces	Tape
0201 / 0603	15000	-	cardboard
0402 / 1005	10000	50000	cardboard
0603 / 1608	4000	16000	cardboard
1003 / 2508	4000	16000	cardboard
0506 / 1216	3000	12000	blister
0508 / 1220	4000	16000	cardboard
0612 / 1632	3000	12000	blister
1012 / 2532	2000	8000	blister

Taping and Packing

Some parts of this publication contain statements about the suitability of our CeraDiodes for certain areas of application, including recommendations about incorporation/design-in of these products into customer applications. The statements are based on our knowledge of typical requirements often made of our CeraDiodes in the particular areas. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our CeraDiodes for a particular customer application. As a rule, TDK Electronics is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always incumbent on the customer to check and decide whether the CeraDiodes with the properties described in the product specification are suitable for use in a particular customer application.

- Do not use TDK Electronics CeraDiodes for purposes not identified in our specifications, application notes and data books.
- Ensure the suitability of a CeraDiode in particular by testing it for reliability during design-in. Always evaluate a CeraDiode under worst-case conditions.
- Pay special attention to the reliability of CeraDiodes intended for use in safety-critical applications (e.g. medical equipment, automotive, spacecraft, nuclear power plant).

Design notes

- Always connect a CeraDiode in parallel with the electronic circuit to be protected.
- Consider maximum rated power dissipation if a CeraDiode has insufficient time to cool down between a number of pulses occurring within a specified isolated time period. Ensure that electrical characteristics do not degrade.
- Consider derating at higher operating temperatures. Choose the highest voltage class compatible with derating at higher temperatures.
- Surge currents beyond specified values will puncture a CeraDiode. In extreme cases a CeraDiode will burst.
- If steep surge current edges are to be expected, make sure your design is as low-inductance as possible.
- In some cases the malfunctioning of passive electronic components or failure before the end of their service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. Do not use CeraDiodes in applications requiring a very high level of operational safety and especially when the malfunction or failure of a passive electronic component could endanger human life or health (e.g. in accident prevention, life-saving systems, or automotive battery line applications such as clamp 30), ensure by suitable design of the application or other measures (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of such a malfunction or failure.
- Specified values only apply to CeraDiodes that have not been subject to prior electrical, mechanical or thermal damage. The use of CeraDiodes in line-to-ground applications is therefore not advisable, and it is only allowed together with safety countermeasures like thermal fuses.

Taping and Packing

Storage

- Only store CeraDiodes in their original packaging. Do not open the package before storage.
- Storage conditions in original packaging: temperature -25 to $+45^{\circ}\text{C}$, relative humidity $\leq 75\%$ annual average, maximum 95%, dew precipitation is inadmissible.
- Do not store CeraDiodes where they are exposed to heat or direct sunlight. Otherwise the packaging material may be deformed or CeraDiodes may stick together, causing problems during mounting.
- Avoid contamination of the CeraDiode surface during storage, handling and processing.
- Avoid storing CeraDiodes in harmful environments where they are exposed to corrosive gases for example (SO_x , Cl).
- Use CeraDiodes as soon as possible after opening factory seals such as polyvinyl-sealed packages.
- Solder CeraDiodes after shipment from TDK Electronics within the time specified: 12 months.

Handling

- Do not drop CeraDiodes and allow them to be chipped.
- Do not touch CeraDiodes with your bare hands - gloves are recommended.
- Avoid contamination of the CeraDiode surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

Mounting

- When CeraDiodes are encapsulated with sealing material or overmolded with plastic material, be aware that potting, sealing or adhesive compounds can produce chemical reactions in the CeraDiode ceramic that will degrade its electrical characteristics and reduce its lifetime.
- Make sure an electrode is not scratched before, during or after the mounting process.
- Make sure contacts and housings used for assembly with CeraDiodes are clean before mounting.
- The surface temperature of an operating CeraDiode can be higher. Ensure that adjacent components are placed at a sufficient distance from a CeraDiode to allow proper cooling.
- Avoid contamination of the CeraDiode surface during processing.
- Only CeraDiodes with an Ni barrier termination are approved for lead-free soldering.

Soldering

- Complete removal of flux is recommended to avoid surface contamination that can result in an instable and/or high leakage current.
- Use resin-type or non-activated flux.
- Bear in mind that insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended, otherwise a component may crack.

Taping and Packing

Operation

- Use CeraDiodes only within the specified operating temperature range.
- Use CeraDiodes only within specified voltage and current ranges.
- Environmental conditions must not harm a CeraDiode. Only use them in normal atmospheric conditions. Reducing the atmosphere (e.g. hydrogen or nitrogen atmosphere) is prohibited.
- Prevent a CeraDiode from contacting liquids and solvents. Make sure that no water enters a CeraDiode (e.g. through plug terminals).
- Avoid dewing and condensation.
- TKD Electronics CeraDiodes are designed for encased applications. Under all circumstances avoid exposure to:
 - direct sunlight
 - rain or condensation
 - steam, saline spray
 - corrosive gases
 - atmosphere with reduced oxygen content
- TKD Electronics CeraDiodes are not suitable for switching applications or voltage stabilization where static power dissipation is required.

This listing does not claim to be complete, it merely reflects the experience of TDK Electronics AG.

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the website, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.** Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.